

Amendments to the Specification:

Please replace the paragraph beginning at page 3, line 26, with the following redlined paragraph:

Flexible substrates 12 may be composites of commercially available materials. For example, the Dupont Pyralux series is commonly used for the various insulating layers in the substrate 12. The substrate 12 may have multiple layers of the substrate material to accommodate high densities of circuit traces, with the electrical traces 20 being formed on the outer surfaces of the substrate 12 as well as sandwiched between internal layers. The flexibility of the connector is affected by the number of layers, the thickness of the layers, the adhesives used to bond multiple layers, the coatings on the surfaces of the connector and the overall dimensions of the connector. The number of layers and stiffness of the substrate is chosen to protect the connector 10 and traces 20 from damage caused by excessive flexing and by abrasion. If many layers are needed, due to the complexity of the circuit ~~or~~ or the protection needed, the substrate 12 may be stiffer than desired for the electrical properties.

Please replace the paragraph (or section) beginning at page 10, line 23, with the following redlined paragraph:

Figure 10F shows relatively small strain relief structures 52 aligned in the spaces between the contact pads both horizontally and vertically. This will provide decoupling at pads 14 ~~in of~~ in of the same row ~~from each other~~, as well as ~~in of~~ in of adjacent rows. ~~Of this will~~ Such decoupling may be desired in many applications. Alternatively, the apertures 52 between rows will not be present and only apertures 52 between pads 14 in the same row will be used. This will provide a focus of support as desired. As can be seen, the location, size, slope an/or configuration of apertures 52 can be selected to provide the desired focus of support while at the same time adding the desired decoupling to provide the correct amount of local flexibility.